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FOR IMMEDIATE RELEASE

Press Release

YINCAE Launches UF 66L Optical Clear Underfill for High-Reliability Silicon Photonics and Optoelectronic Packaging

(Albany, NY) 10/08/2025 — YINCAE is proud to announce the release of UF 66L, a next-generation Optical Clear Underfill (OCU) engineered for silicon photonics, optoelectronic packaging, image sensors, AR/VR modules, and advanced flip-chip assemblies where optical clarity, thermal endurance, and reliability are critical.

Technical Performance Highlights:

- ❖ **Thermal Endurance:** Withstands 5×260 °C reflow cycles without cracking, delamination, or adhesion loss.
- ❖ **Optical Transparency:** Maintains >95% light transmittance (400–800 nm), ensuring minimal signal loss through optical pathways.
- ❖ **Non-Yellowing Stability:** Exceptional resistance to discoloration after repeated high-temperature exposure.
- ❖ **Reliability:** Excellent adhesion to silicon, glass, and substrate materials for enhanced package durability.
- ❖ **Mechanical Properties:** Controlled modulus formulation reinforces delicate structures while minimizing stress and warpage.

UF 66L overcomes the limitations of conventional epoxy underfills, which often lose transparency or degrade under thermal cycling. It is specifically optimized for optical interconnect stability, waveguide coupling, photodetectors, and high-density optoelectronic packaging, enabling reliable performance in next-generation devices. "UF 66L provides engineers with a robust, optically clear underfill that maintains mechanical integrity and optical performance under demanding processing and operational conditions," said CTO at YINCAE.

For more information on YINCAE's UF 66L, or to learn more about what YINCAE offers, please email us at: info@yincae.com. You can also find more information by visiting our website at: www.yincae.com

Founded in 2005 & headquartered in Albany, New York, YINCAE Advanced Materials is a leading manufacturer and supplier of thermal interface materials, underfill solutions, die attach adhesives, electronic materials, & high-performance coatings used in microchip & optoelectronic devices. YINCAE products provide new technologies to support manufacturing processes from wafer level, to package level, to board level and final devices while facilitating smarter and faster production and supporting green initiatives.

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